

ABSTRACT OF THE DISCLOSURE

The present invention generally is directed to a method of electrochemically and mechanically planarizing a surface of a substrate, comprising: providing a basin containing an electrically conductive solution and an electrode disposed therein, disposing a polishing medium in the electrically conductive solution, positioning a substrate against the polishing medium so that a surface of the substrate contacts the electrically conductive solution, applying a first potential between the polishing medium and the electrode for a first time period, and applying a second potential between the polishing medium and the electrode for a second time period.